Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.						This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date* 2023-06-08 Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards	752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Ty					e *										
Contact Name Title - Contact Product-Env-Stewards P	upplier	Information															
Title - Contact Phone - Contact* Phone - Contact* Product-Env-Stewards Product-Env-Stewards @onsemi.com	ompany r	name*		Company un	ique ID		ī	Unique ID Au	uthority	,			Response	Date*	:		
Product-Env-Stewards Authorized Representative* Authorized Representative* Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM GBPC2504W BR GBPCW GPPN 25A 400V 2023-06-08 TSCBE 16949.998 mg Terminal Plating / Grid Array Material Terminal Base Alloy Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM TSCBE 16949.998 mg Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3	ısemi												2023-06-0)8			
Authorized Representative* Product Env-Stewards Product Enviro Compliance Requester Item Number Requester Item Number Representative* Representative* Representative* Representative* Representative* Representative* Representative* Representative* Representative* Requester Item Number Representative* Representative* Representative* Representative* Requester Item Number Representative* Requester Item Number Representative* Requester Item Number Representative* Requester Item Number Representative* Representative* Requester Item Number Requester Item Number Representative* Requester Item Number Requ	ontact Na	ame		Title - Contac	ct]	Phone - Cont	tact*	·			Email - C	ontact	t*	·	
Product-Env-Stewards Product-Env-Stewards	roduct-E	nv-Stewards		Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				<u>m</u>
Requester Item Number	Authorized Representative* Ti				Title - Representative			Phone - Representative*				Email - Representative*					
GBPC2504W BR GBPCW GPPN 25A 400V 2023-06-08 TSCBE 16949.998 mg I	roduct-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3		Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Da	ate Ve	ersion	Manufactu	uring Site	W	eight*	U	JOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3			GBPC2:	504W	BR GBPCW GP	PN 25A 400V		2023-06-08		,	TSCBE		10	5949.99	98 m	ng	Each
Precious metal (e.g. Ag,Au, NiPdAu) (no CU Alloy NA 0 C 30 seconds 3	Ianufac	eturing Proccess Information	tion														
	,	Terminal Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MS	TD-020 MSL Rating		Peak Process Body Temperatur		nre Max Time at Peak Tempera		Temperatu	re Number of Reflow Cycles		les	
			PdAu) (no	CU Alloy		NA		0		С	30		second	s 3			
Comments	omments																

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the par contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledges and belie as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member states that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting tempe Exemption: 7c-I Electrical and electronic c	erature type solders (i.e. lead based solder omponents containing lead in a glass or co	r alloys containing 85% by weight or more lead) ceramic other than dielectric ceramic in capacito	rs, e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.						
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required in Requester) and click on Submit Form to ha		"Accepted" on the Supplier Acceptance drop-do	wn. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature R		,								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Case	2949.3	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		589.8748	mg
			Supplier	Silica (SiO2)	14464-46-1		2064.5603	mg
			Supplier	Phosphorus (P)	7723-14-0		58.9152	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		235.9497	mg
Die	33.561	mg	Supplier	Silicon (Si)	7440-21-3		30.2049	mg
			В	Nickel (Ni)	7440-02-0		0.2181	mg
			Supplier	Gold (Au)	7440-57-5		0.0503	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	3.0876	mg
Die Attach Solder	18.1365	mg	Supplier	Silver (Ag)	7440-22-4		0.4534	mg
			A	Lead (Pb)	7439-92-1	7a	16.7763	mg
			Supplier	Tin (Sn)	7440-31-5		0.9068	mg
Die Attach Solder - Solder Wafer	82.8855	mg	Supplier	Silver (Ag)	7440-22-4		2.0721	mg
			A	Lead (Pb)	7439-92-1		76.6691	mg
			Supplier	Tin (Sn)	7440-31-5		4.1443	mg
Heat Sink	3803.24	mg	Supplier	Aluminum (Al)	7429-90-5		3803.24	mg
Lead Frame	1220.4	mg	Supplier	Iron (Fe)	7439-89-6		0.9763	mg
			Supplier	Copper (Cu)	7440-50-8		1219.1797	mg
			Supplier	Phosphorus (P)	7723-14-0		0.244	mg
Marking Ink	0.5085	mg	Supplier	Silicon Dioxide (SiO2)	112945-52-5		0.0254	mg
			Supplier	1-Hydroxycyclohexyl phenyl ketone	947-19-3		0.0254	mg
			Supplier	Padimate (C14H21NO2)	21245-01-2		0.0509	mg
			Supplier	2-Propenoic acid polymer	53192-18-0		0.3305	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0763	mg
Mold Compound-White	6552.36	mg		Polymer Resin	proprietary data		1092.2784	mg
			Supplier	1,2-Bis(pentabromophenyl) ethane	84852-53-9		382.0026	mg
			Supplier	Brominated epoxy resin	Proprietary Data		1419.8964	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		218.1936	mg
			Supplier	Carbon Black (C)	1333-86-4		54.3846	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		655.236	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2730.3682	mg
Plating-2	14.916	mg	В	Nickel (Ni)	7440-02-0		14.916	mg
Terminal	2274.69	mg	Supplier	Iron (Fe)	7439-89-6		2.7296	mg

	Supplier	Copper (Cu)	7440-50-8	2270.9822	mg
	Supplier	Phosphorus (P)	7723-14-0	0.9781	mg